

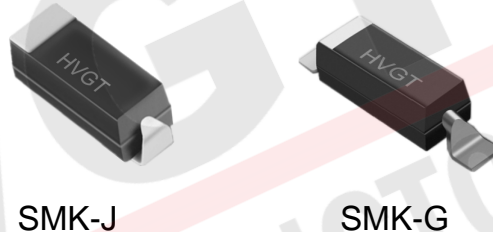
Features:

Surface Mount Package.
 J Lead or Gullwing Package Option.
 Molded Plastic Body, ANSI/UL94 V-0 Rated Material.

Application:

X-ray Power Supply.
 High Voltage Multiplier Circuit.
 Other High Voltage Rectifier Circuits.

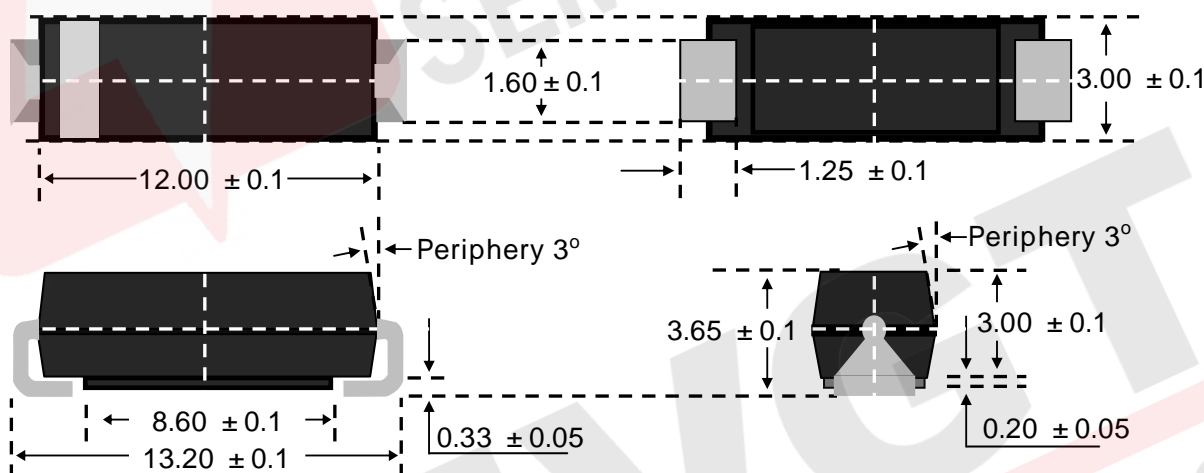
Reference Shape:



Drawings: (Unit:mm)

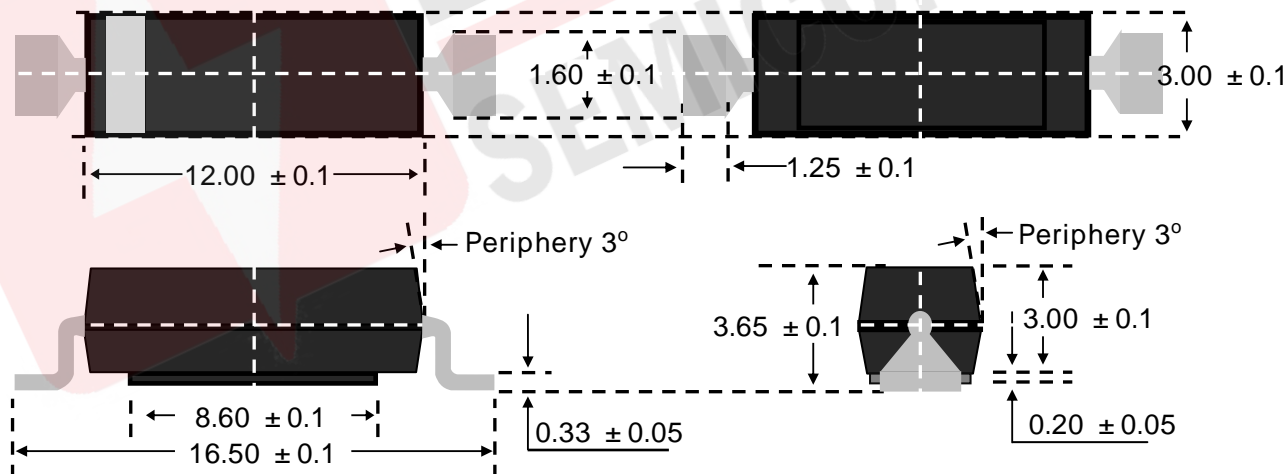
SMK-J Series

SMK-J Lead



SMK-G Series

SMK-G Lead



Maximum Ratings And Characteristics: (25°C ambient temperature unless stated otherwise.)

HVGT Part Number	V _{RRM} kV	I _{FAVM} mA	V _F V	I _R uA	I _{FSM} A	T _{RR} nS	C _J pF	R _{JL} °C/W	R _{JC} °C/W
SMK-J Series									
SM37L05J	5.0	550	12	2.0	15	100	6.5	16	30
SM37L06J	6.0	500	13	2.0	15	100	5.0	16	30
SM37L08J	8.0	450	16	2.0	15	100	4.5	16	30
SM37L10J	10.0	400	20	2.0	15	100	3.5	16	30
SM37L12J	12.0	350	24	2.0	15	100	2.7	16	30
SM37L15J	15.0	200	27	2.0	15	100	2.1	16	30
SM37L20J	20.0	150	35	2.0	15	100	1.8	16	30
SM37L25J	25.0	100	40	2.0	15	100	1.5	16	30

SMK-G Series									
SM37L05G	5.0	550	12	2.0	15	100	6.5	16	30
SM37L06G	6.0	500	13	2.0	15	100	5.0	16	30
SM37L08G	8.0	450	16	2.0	15	100	4.5	16	30
SM37L10G	10.0	400	20	2.0	15	100	3.5	16	30
SM37L12G	12.0	350	24	2.0	15	100	2.7	16	30
SM37L15G	15.0	200	27	2.0	15	100	2.1	16	30
SM37L20G	20.0	150	35	2.0	15	100	1.8	16	30
SM37L25G	25.0	100	40	2.0	15	100	1.5	16	30

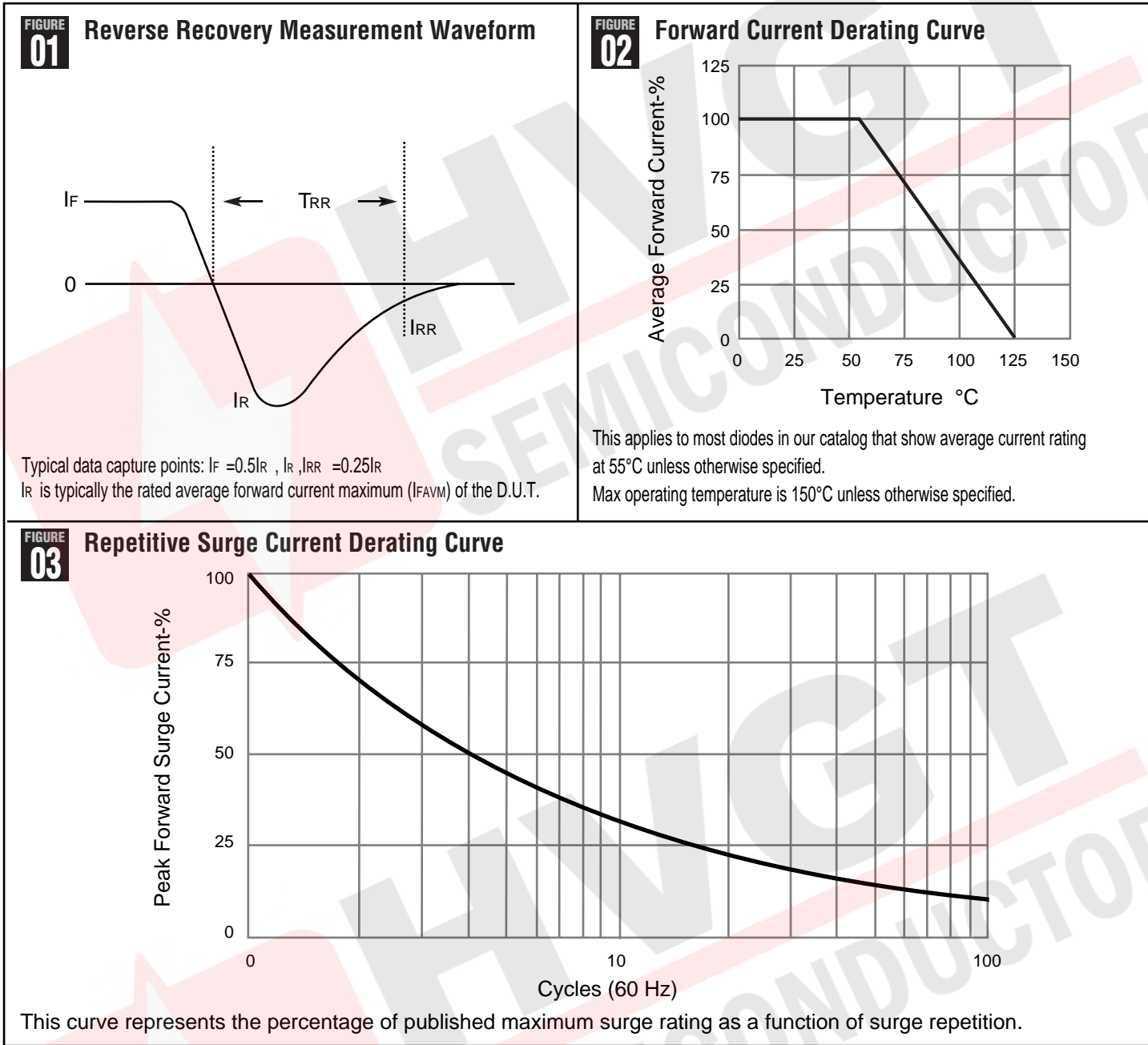
Temperature:

Storage Temperature -55 to 175 °C
 Operating Temperature -55 to 125 °C
 Maximum Junction Temperature 125 °C

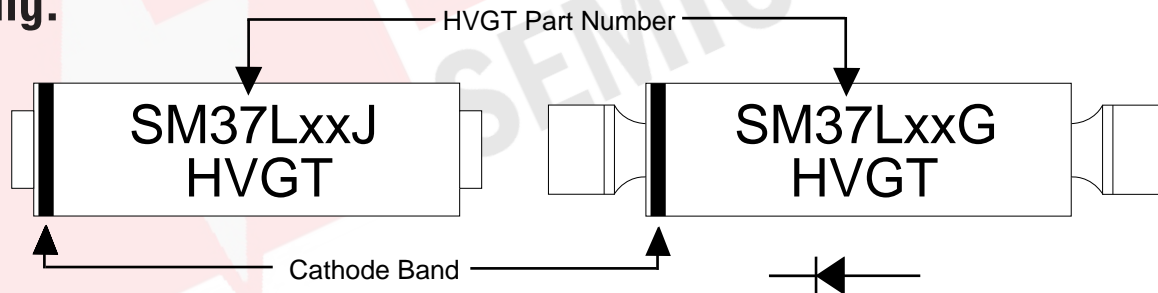
Specification Definitions:

Symbols	Items	Condition
V _{RRM}	Maximum Repetitive Reverse Voltage	--
I _{FAVM}	Maximum Average Forward Current	At T _L = 55°C
V _F	Maximum Forward Voltage Drop	At I _{FAVM}
I _R	Maximum Leakage Current	At V _{RRM}
I _{FSM}	Maximum Surge Current	At 8.3 mS, Single Half Sine
T _{RR}	Maximum Reverse Recovery Time	I _F = 0.5 I _{FAVM} ; I _R = -I _{FAVM} ; I _{RR} = -0.25 I _{FAVM}
C _J	Typical Junction Capacitance	At V _R = 0VDC, f = 1MHz
R _{JL}	Typical Thermal Resistance Junction to Lead	Device Mounted on 0.2" x 0.2" (5mm x 5mm) Copper Solder Pads
R _{JC}	Typical Thermal Resistance Junction to Case	

Curves Diagram:



Marking:



Note:

Specifications subject to change without notice. Photo is representation only.
 Standard package quantity: 1,000PCS
 Specifications based on diode P.C.B. mounted on 5.0 mm x 5.0 mm copper solder pads.